



# SOT878-1

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 27 leads, (row spacing 2.54 mm)

10 April 2018

Package information

## 1. Package summary

<b>Terminal position code</b>	Z (zig-zag)
<b>Package type descriptive code</b>	RDBS27P
<b>Package type industry code</b>	RDBS27P
<b>Package style descriptive code</b>	RDBS (right-angle DIL-bent-SIL)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	T (through-hole mount)
<b>Issue date</b>	19-12-2012
<b>Manufacturer package code</b>	SOT878

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	28.8	-	29	29.2	mm
E	package width	15.5	-	15.7	15.9	mm
A <sub>2</sub>	package height	4.4	-	4.5	4.6	mm
e	nominal pitch	-	-	2	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	27	-	A/A



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## 2. Package outline

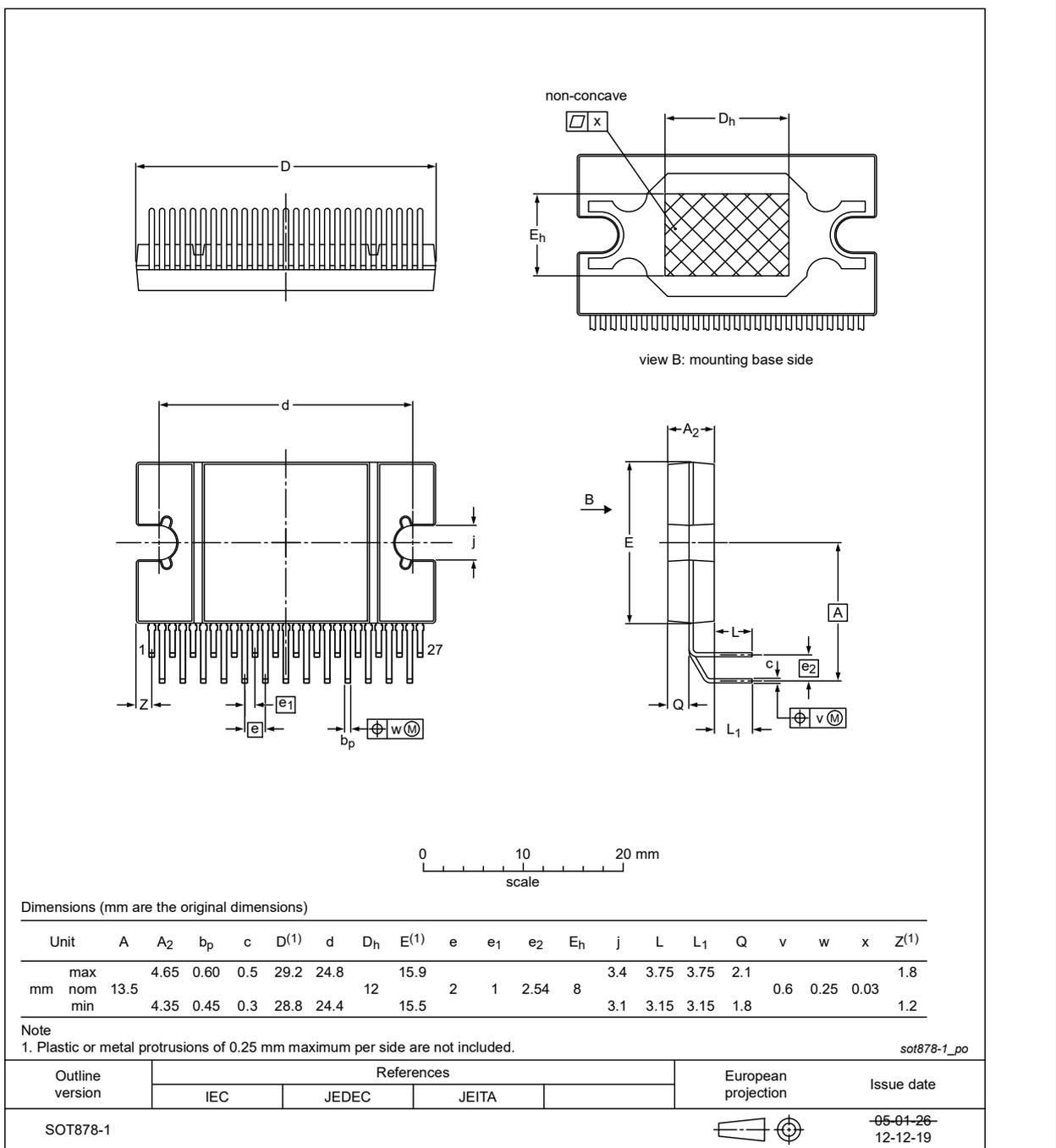


Fig. 1. Package outline RDBS27P (SOT878-1)

plastic rectangular-DIL-bent-SIL (reverse bent) power package; 27 leads, (row spacing 2.54 mm)

### 3. Soldering

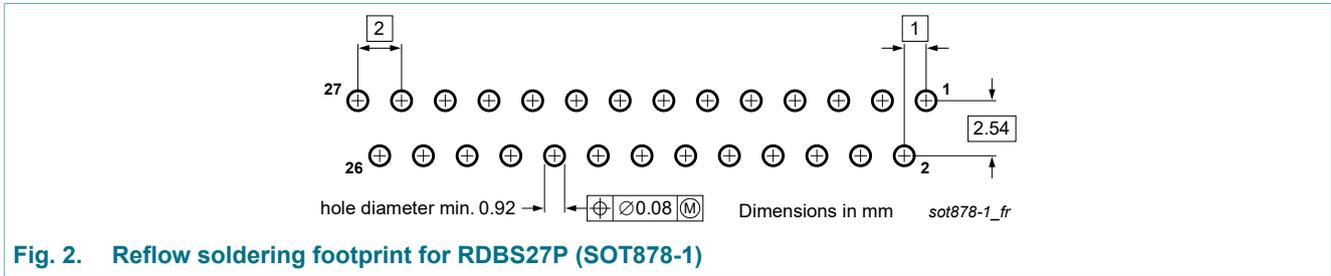


Fig. 2. Reflow soldering footprint for RDBS27P (SOT878-1)

## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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